

N-Channel 20 V (D-S) MOSFET

PRODU	PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^e	2 (T)	l Մ2113G		
	0.028 at $V_{GS} = 4.5 \text{ V}$	6 ^a				
20	0.042 at V _{GS} = 2.5 V	6 ^a	8.8 nC			
	0.050 at V _{GS} = 1.8 V	5.6		,		

FEATURES

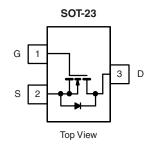
- Halogen-free According to IEC 61249-2-21
 hition
- TrenchFET[®] Power MOSFET
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC



ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

- DC/DC Converters
- Load Switch for Portable Applications



ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted					
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V_{DS}	20	V	
Gate-Source Voltage		V_{GS}	± 12	v	
	T _C = 25 °C		6 ^a		
Continuous Drain Comment (T. 150 °C)	T _C = 70 °C	I _D	5.1		
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C		5 ^{b, c}		
	T _A = 70 °C		4 ^{b, c}	A	
Pulsed Drain Current		I _{DM}	20		
Continuous Course Prain Diade Current	T _C = 25 °C		1.75		
Continuous Source-Drain Diode Current	T _A = 25 °C	l _S	1.04 ^{b, c}		
	T _C = 25 °C		2.1		
Maximum Power Dissipation	T _C = 70 °C	P _D	1.3	w	
Maximum Fower Dissipation	T _A = 25 °C		1.25 ^{b, c}	VV	
	T _A = 70 °C	•	0.8 ^{b, c}		
Operating Junction and Storage Temperatur	e Range	T _J , T _{stg}	- 55 to 150	°C	
Soldering Recommendations (Peak Tempera	ature)	Ĭ	260		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, d}	t ≤ 5 s	R _{thJA}	80	100	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	40	60] 5/**	

Notes:

- a. Package limited
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 5 s
- d. Maximum under steady state conditions is 125 $^{\circ}\text{C/W}.$
- e. Based on T_C = 25 °C.

服务热线:400-655-8788

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SPECIFICATIONS $T_J = 25 ^{\circ}C$,	uniess otne	rwise noted				,	
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V, } I_D = 250 \mu\text{A}$	20			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		25		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_{J}$			- 2.6			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_{D} = 250 \mu A$	0.45		1.0	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA	
	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0 V			1	μΑ	
Zero Gate Voltage Drain Current		V _{DS} = 20 V, V _{GS} = 0 V, T _J = 70 °C			10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	20			Α	
		$V_{GS} = 4.5 \text{ V}, I_D = 5.0 \text{ A}$		0.028	 		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 2.5 V, I _D = 4.7 A		0.042		Ω	
		$V_{GS} = 1.8 \text{ V}, I_D = 4.3 \text{ A}$		0.050		1	
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 10 \text{ V}, I_D = 5.0 \text{ A}$		24		S	
Dynamic ^b			ı				
Input Capacitance	C _{iss}			865			
Output Capacitance	C _{oss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		105		pF	
Reverse Transfer Capacitance	C _{rss}	20 7 00		55			
Tieveree Handler Capacitaine		V _{DS} = 10 V, V _{GS} = 5 V, I _D = 5.0 A		12	18		
Total Gate Charge	Qg	26 7 40 7 2		8.8	14	nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 5.0 \text{ A}$		1.1			
Gate-Drain Charge	Q _{gd}	50 7 do 7 5		0.7			
Gate Resistance	R _g	f = 1 MHz	0.5	2.4	4.8	Ω	
Turn-On Delay Time	t _{d(on)}			8	16		
Rise Time	t _r	V_{DD} = 10 V, R_L = 2.2 Ω		17	26	1	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 4$ A, V_{GEN} = 4.5 V, R_g = 1 Ω		31	47		
Fall Time	t _f			8	16		
Turn-On Delay Time	t _{d(on)}			5	10	ns	
Rise Time	t _r	V_{DD} = 10 V, R_L = 2.2 Ω		13	20	- - -	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 4 \text{ A}, V_{GEN} = 5 \text{ V}, R_g = 1 \Omega$		21	32		
Fall Time	t _f			6	12		
Drain-Source Body Diode Characteristic	cs		<u> </u>	<u> </u>			
Continuous Source-Drain Diode Current	Is	T _C = 25 °C			1.75		
Pulse Diode Forward Current	I _{SM}				20	A	
Body Diode Voltage	V _{SD}	I _S = 4 A, V _{GS} = 0 V		0.75	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}	- 		12	20	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			5	10	nC	
Reverse Recovery Fall Time	t _a	$I_F = 4$ A, $dI/dt = 100$ A/ μ s, $T_J = 25$ °C		7			
Reverse Recovery Rise Time	t _b	-		5		ns	

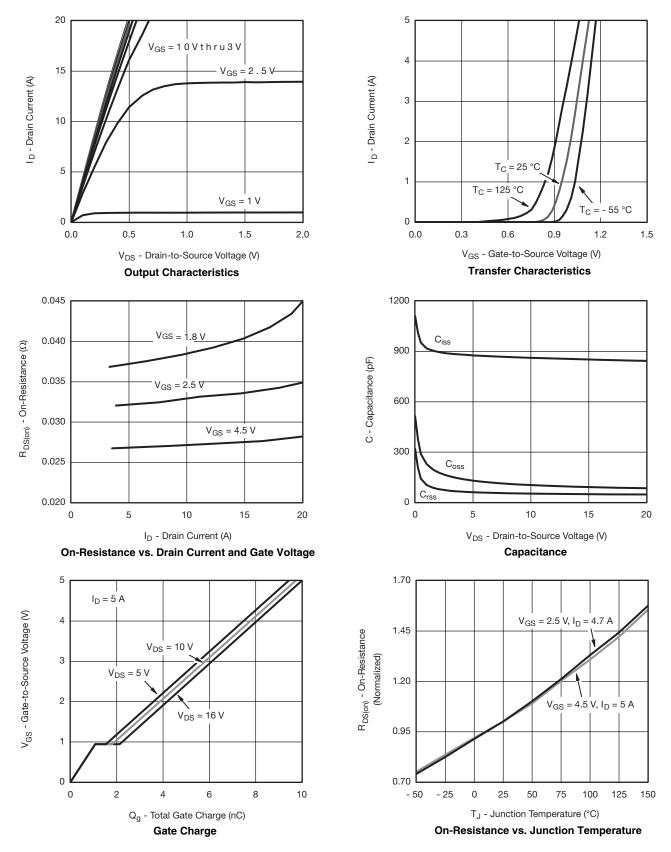
Notes:

- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 % b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

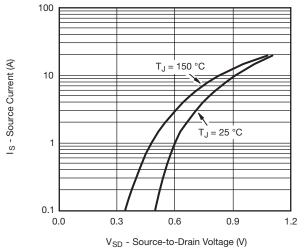


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

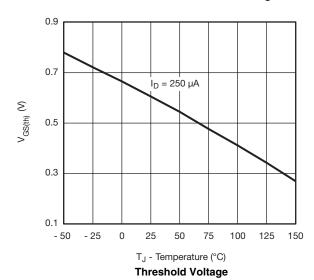


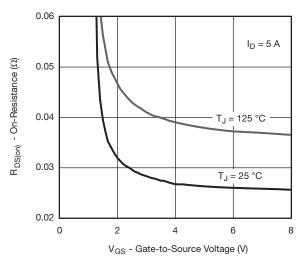


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

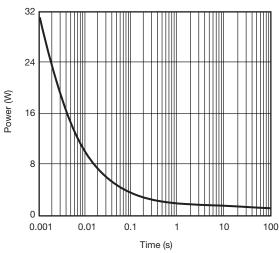


Source-Drain Diode Forward Voltage

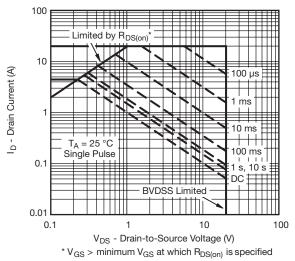




On-Resistance vs. Gate-to-Source Voltage



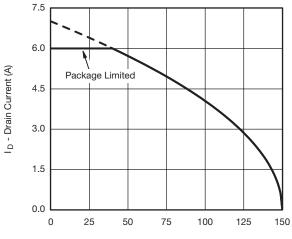
Single Pulse Power (Junction-to-Ambient)



Safe Operating Area, Junction-to-Ambient

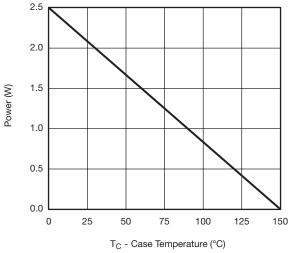


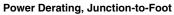
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

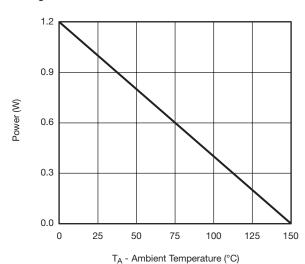


T_C - Case Temperature (°C)

Current Derating*







Power Derating, Junction-to-Ambient

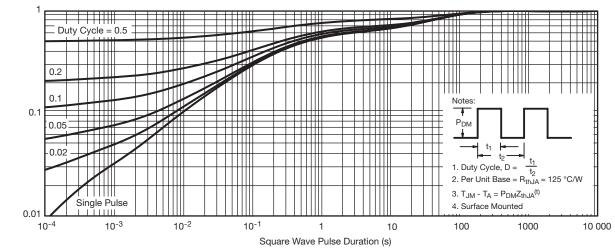
^{*} The power dissipation P_D is based on $T_{J(max.)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

Normalized Effective Transient Thermal Impedance

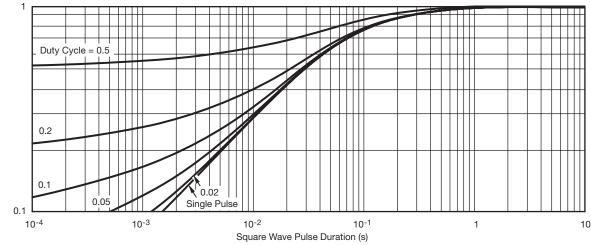
Normalized Effective Transient Thermal Impedance



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



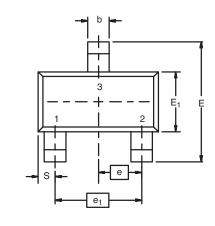
Normalized Thermal Transient Impedance, Junction-to-Ambient

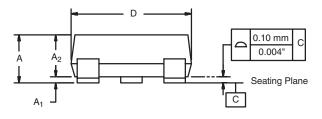


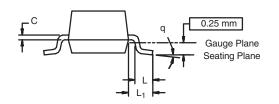
Normalized Thermal Transient Impedance, Junction-to-Foot



SOT-23 (TO-236): 3-LEAD





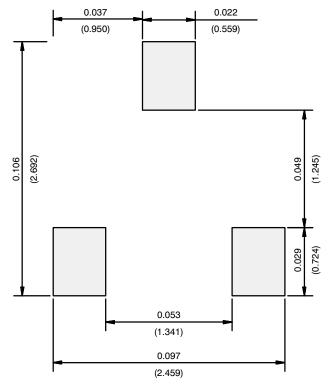


Dim	MILLIM	IETERS	INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A ₁	0.01	0.10	0.0004	0.004	
A ₂	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E ₁	1.20	1.40	0.047	0.055	
е	0.95 BSC		0.0374 Ref		
e ₁	1.90 BSC		0.074	8 Ref	
L	0.40	0.60	0.016	0.024	
L ₁	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	
ECN: S-03946-Rev. K. 09-	Jul-01	•	<u> </u>		

DWG: 5479



RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)



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DMN1017UCP3-7 EFC2J004NUZTDG P85W28HP2F-7071 DMN1053UCP4-7 NTE2384 DMC2700UDMQ-7 DMN2080UCB4-7
DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B IPS60R3K4CEAKMA1 DMN1006UCA6-7 DMN16M9UCA6-7
STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 IPS60R360PFD7SAKMA1
DMN2990UFB-7B SSM3K35CT,L3F IPLK60R1K0PFD7ATMA1 2N7002W-G MCAC30N06Y-TP IPWS65R035CFD7AXKSA1
MCQ7328-TP SSM3J143TU,LXHF DMN12M3UCA6-7 PJMF280N65E1_T0_00201 PJMF380N65E1_T0_00201
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